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То	the Director of the U.S. Patent and Trademark (	103476463	ents or copy thereof.	
IAADI	Name of conveying party(ies):		,	
2008 W	Kyoo-ryon HAHM			
2. 6	Name and Address of receiving party(ies):			
RADEMEN	SAMSUNG ELECTRONICS CO., LTD. 416, Maetan-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do Republic of Korea			
3.	Nature of conveyance:	Marian		
-	X Assignment Security Agreement	Merger Change of Name		
-	Other:			
~	Execution Date(s): <u>January 3, 2008</u>			
4.	Application number(s) or patent number(s):  This document is being filed together with a new application:  (a) The execution date(s) of the application is/are:  (b) The title is: DATA BURST ASSEMBLY APPARATUS AND DATA BURST PROCESSING METHOD THEREOF  OR			
	<ul> <li>☐ This document is being filed after filing</li> <li>(a) Patent Application No(s). 11/971,23</li> <li>(b) Patent No(s). , issued .</li> </ul>			
5.	Name and address of party to whom corres STEIN, MCEWEN & BUI, LLP Attention: <u>Michael D. Stein</u> 1400 Eye St., N.W., Suite 300 Washington, D.C. 20005	pondence concerning docume Our Docket: <u>00</u>		
6.	Total number of applications and patents involved:1			
7.	Total fee (37 CFR 3.41) (\$ 40.00 per Patent or Application in Assignment)  ☑ Enclosed ☐ Authorized to be charged to Deposit Account No. 503333.			
8.	Deposit Account No. 503333: (Any underpayment is authorized to be charged to this Deposit Account) (Attach duplicate copy of this page if paying by deposit account)			
	ael D. Stein, Reg. No. 37,240	Mule Oslic	1/11/08	
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	DO NO	Total number of pages	including cover sheet: 2	
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PATENT REEL: 020391 FRAME: 0356

Attorney Docket No.: 0005.1245

## **U.S. ASSIGNMENT**

SMB 12/04

**RECORDED: 01/11/2008** 

IN CONSIDERATION of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter, "ASSIGNOR") by

(Insert Name(s) & Address(es) of ASSIGNEE(S))

SAMSUNG ELECTRONICS CO., LTD. 416, Maetan-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do Republic of Korea

(hereinafter, "ASSiGNEE"), the receipt of which is hereby acknowledged, the undersigned ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE the entire and exclusive right, title and interest to the invention entitled (Title of Invention)

## DATA BURST ASSEMBLY APPARATUS AND DATA BURST PROCESSING METHOD THEREOF

relating to International Patent Application PCT/JP_ was executed on even date herewith or, if not so ex		oplication for Letters Patent of the United States
(a) executed on ;	(Insert date of execution of	of application, if not concurrent)
(b) filed on , Application No. Not yet assigned;	St., N.W., Suite 300, Was	STEIN, MCEWEN & BUI, LLP, 1400 Eye hington, D.C. 20005 (202/216-9505) is at in (b) the specified data, when known.
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and to said application and all Letters Patent(s) of the substitute, reissue or reexamination application bat granted and including any extensions thereof (colle	sed thereon, for the full term or term	for which the said Letters Patent(s) may be
o do all acts which the ASSIGNEE may deem nece said invention, including in the preparation and pr	ssary, desirable or expedient, for sec esecution of said application(s) and	the issuance of said Letters Patent(s), in any
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IN WITNESS WHEREOF, the undersigned inve (Typed Name & Signature of Inventor(s))	ntor(s) has (have) affixed his/her/the (Date)	oir signature(s). (Typed Name & Signature of Witness(es))
Kyoo-ryon HAHM	January 3, 2008	Whole
2)		Eun-ji LEE
3)		
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9)		
5)		

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